

ABSTRACT

SUBSTRATE FOR FRONT SIDE TYPE IMAGER
AND METHOD OF MANUFACTURING SUCH A SUBSTRATE

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The invention relates to a substrate for a front side type imager, successively comprising a semiconductor support substrate (1), an electrically insulating layer (2) and a semiconductor active layer (3), characterised in that the active layer (3) is an epitaxial layer made of silicon-germanium whose germanium content is less than 10%.

10 The invention also relates to a method of manufacturing such a substrate.

Figure 2